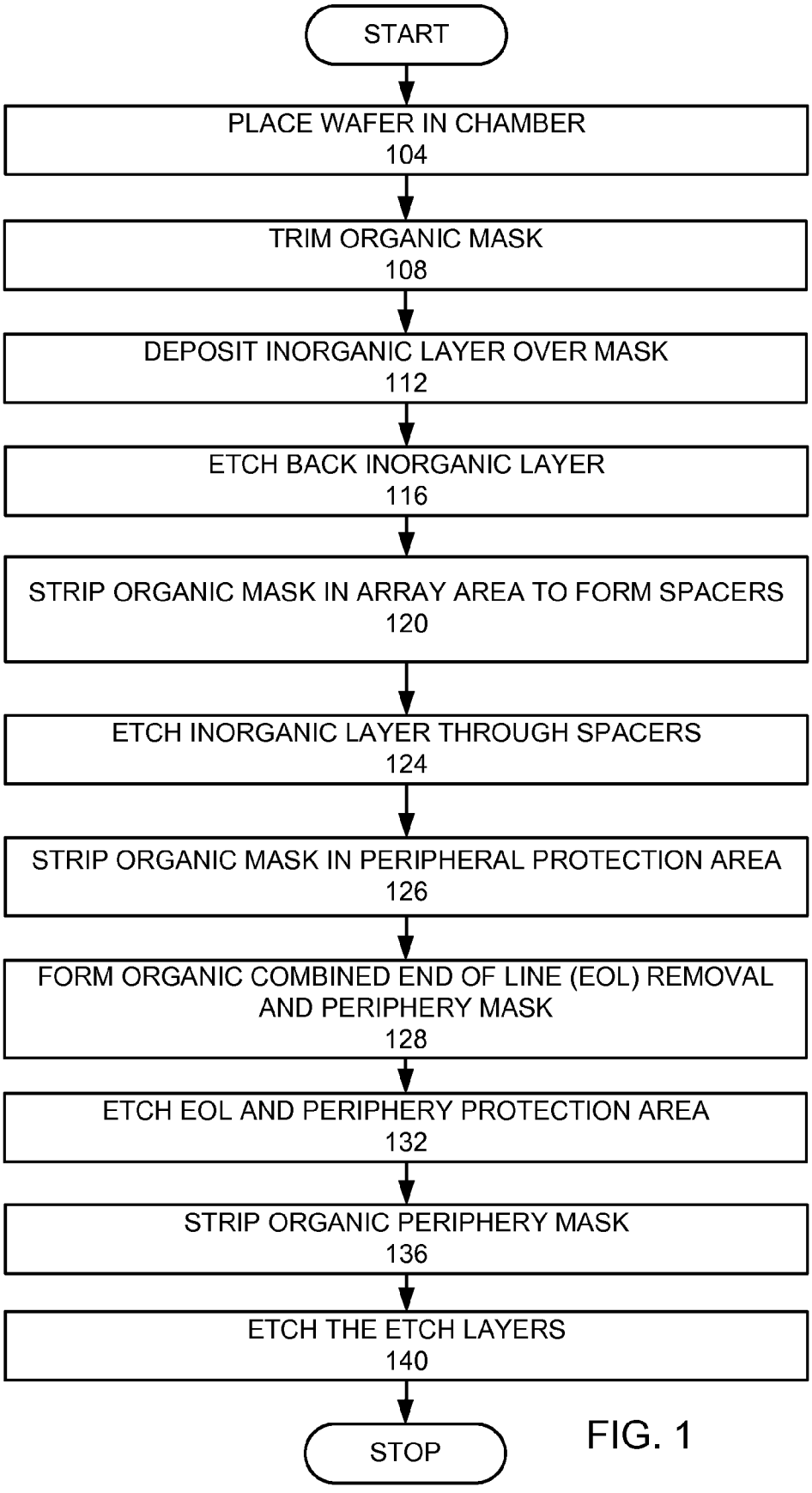

START
PLACE WAFER IN CHAMBER
104
TRIM ORGANIC MASK
108
DEPOSIT INORGANIC LAYER OVER MASK
112
ETCH BACK INORGANIC LAYER
116
STRIP ORGANIC MASK IN ARRAY AREA TO FORM SPACERS
120
ETCH INORGANIC LAYER THROUGH SPACERS
124
STRIP ORGANIC MASK IN PERIPHERAL PROTECTION AREA
126
FORM ORGANIC COMBINED END OF LINE (EOL) REMOVAL AND PERIPHERY MASK
128
ETCH EOL AND PERIPHERY PROTECTION AREA
132
STRIP ORGANIC PERIPHERY MASK
136
ETCH THE ETCH LAYERS
140
STOP

FIG. 1

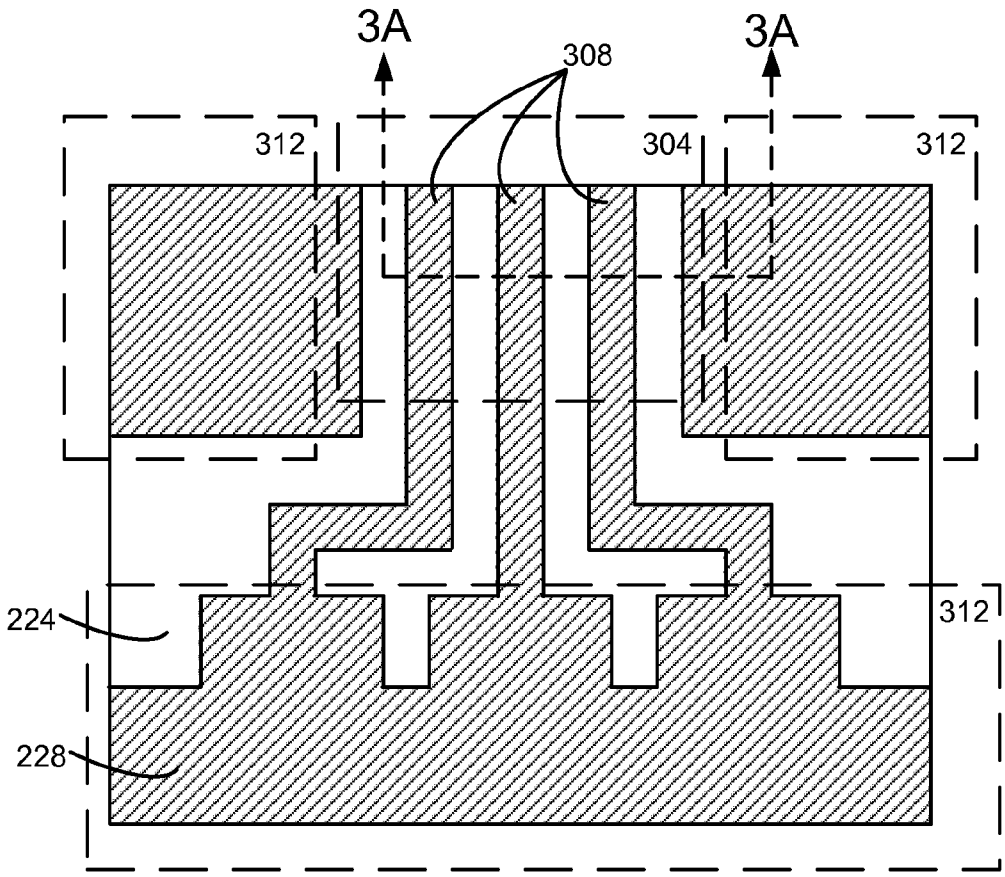

3A
3A
308
312
304
312
224
312
228

FIG. 2A

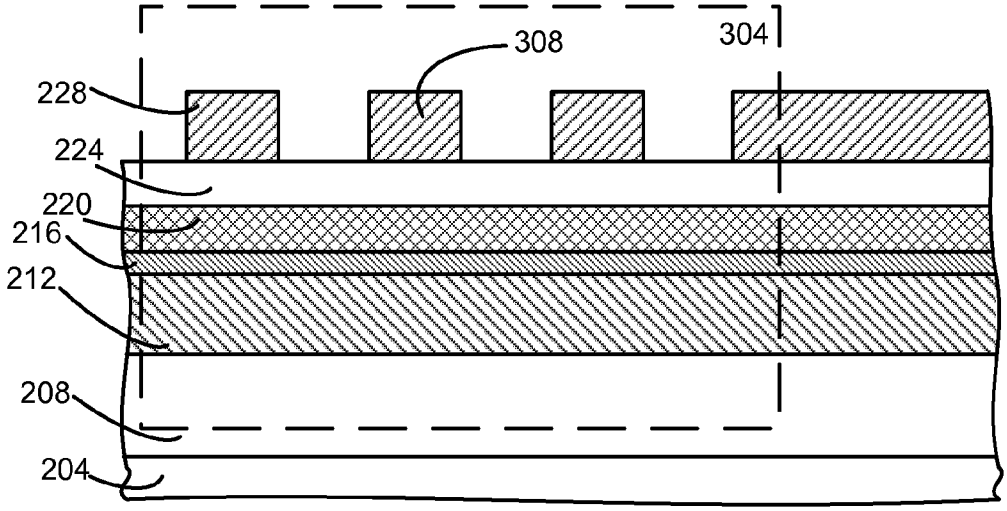

308
304
228
224
220
216
212
208
204

FIG. 3A

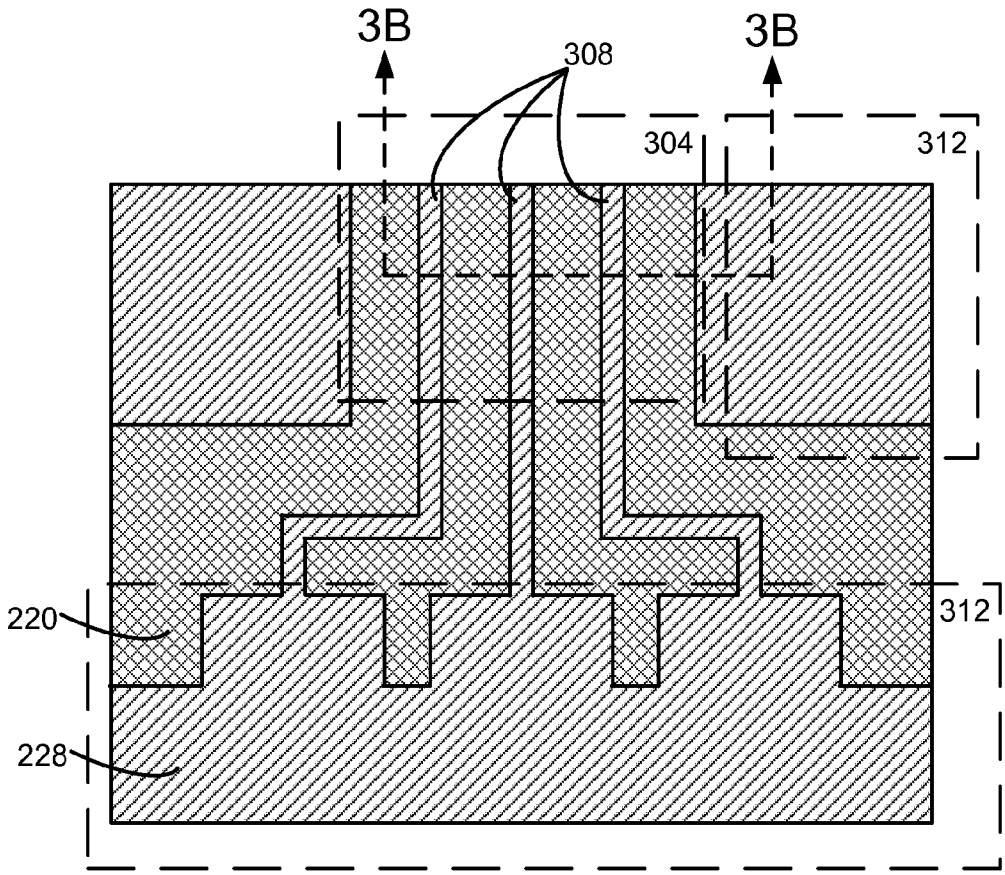


FIG. 2B

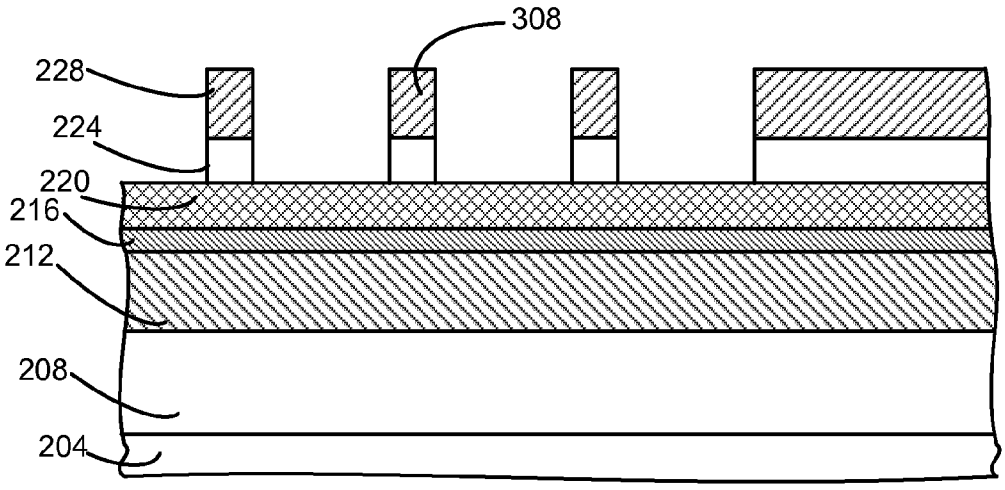


FIG. 3B

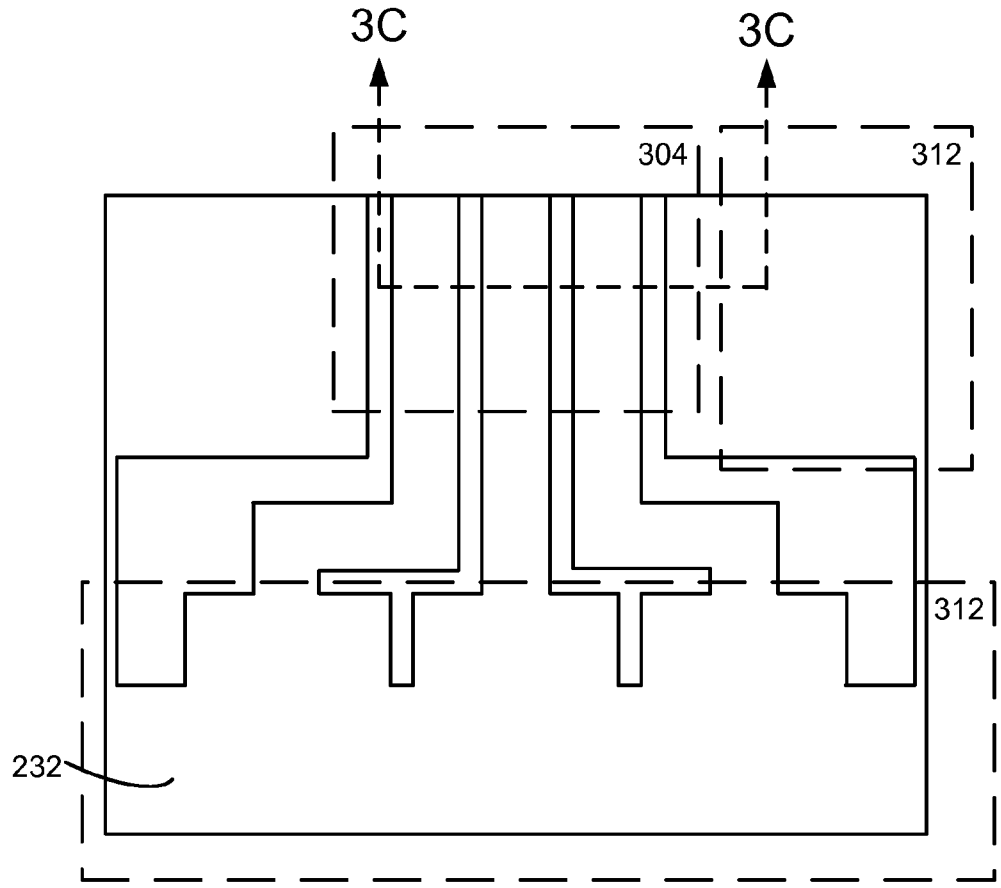


FIG. 2C

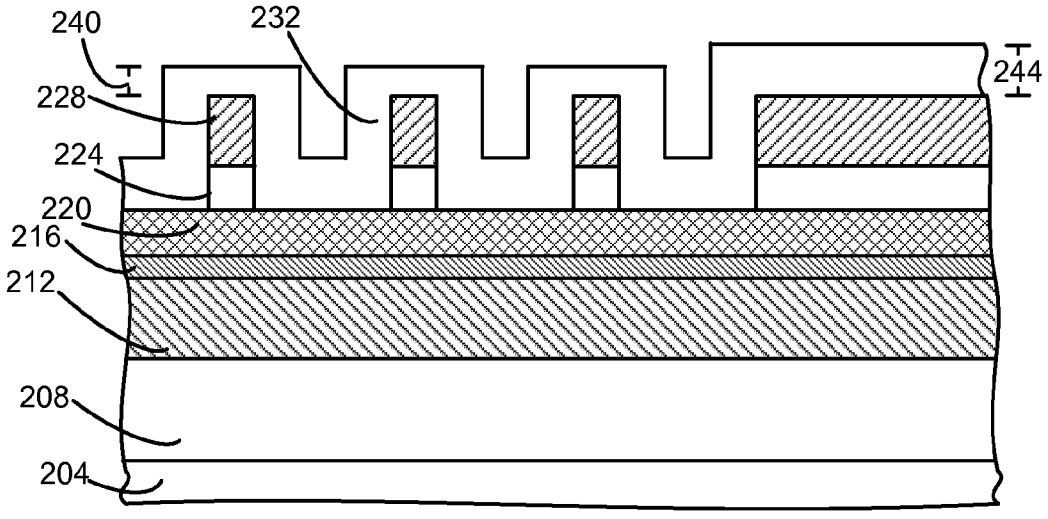


FIG. 3C

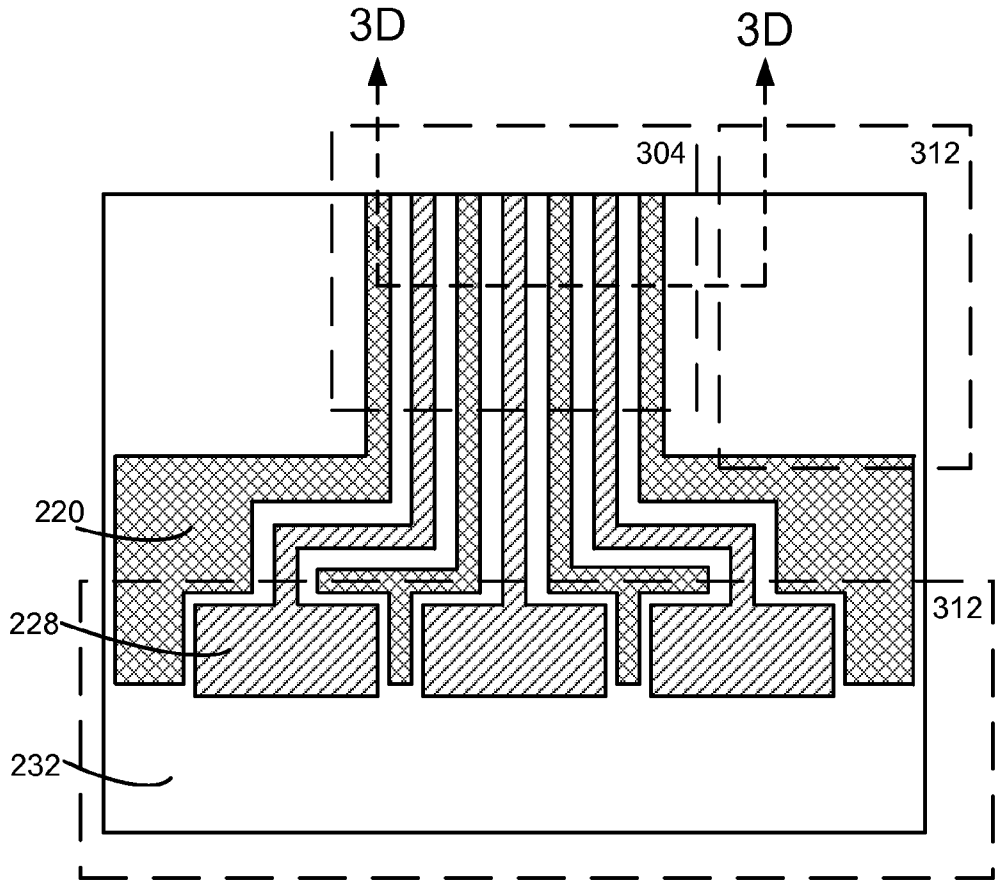


FIG. 2D

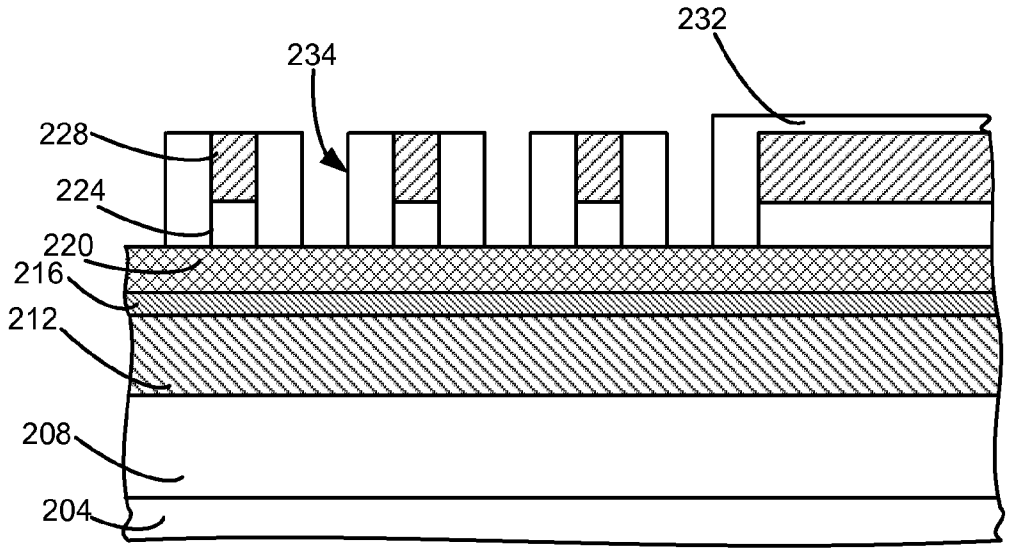


FIG. 3D

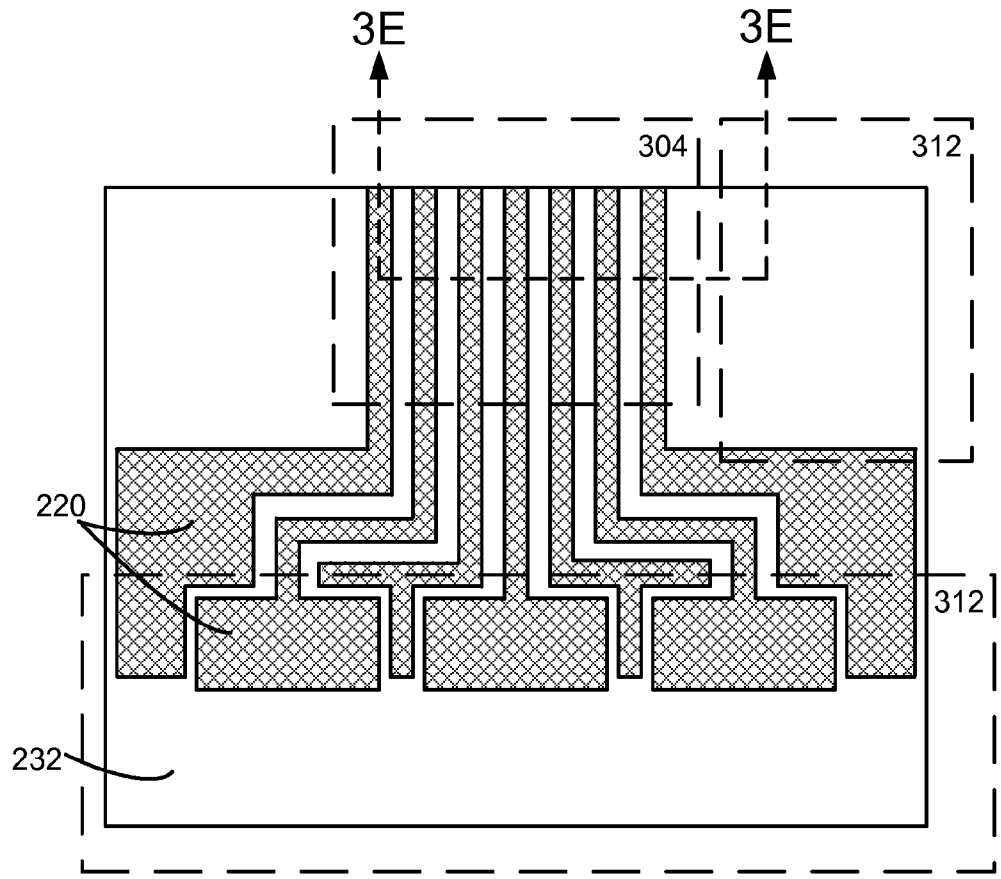


FIG. 2E

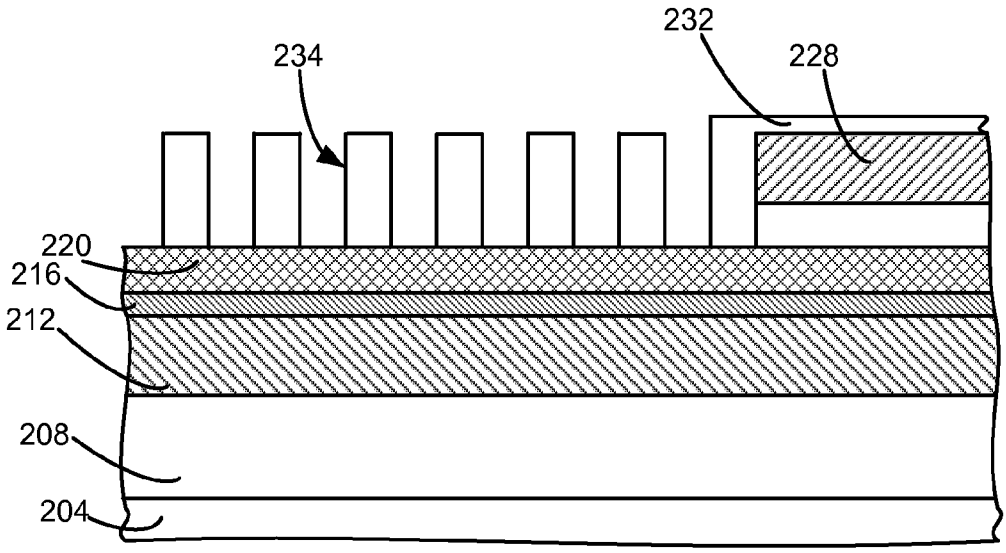


FIG. 3E

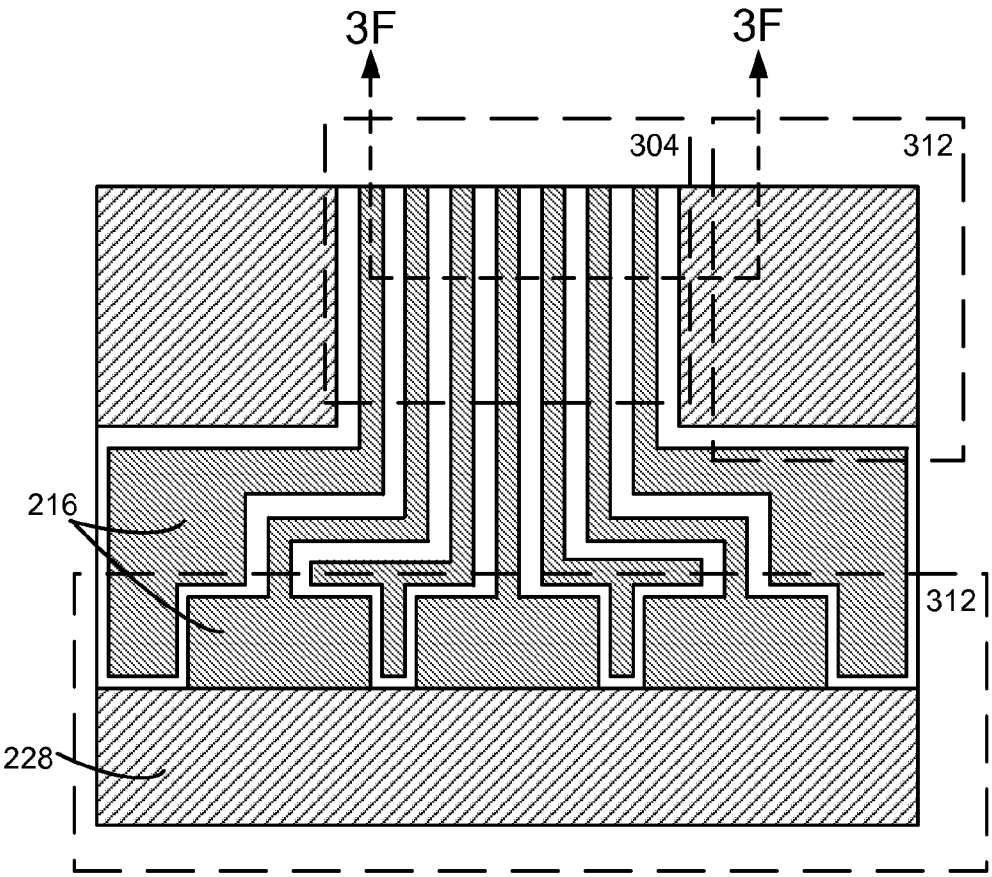


FIG. 2F

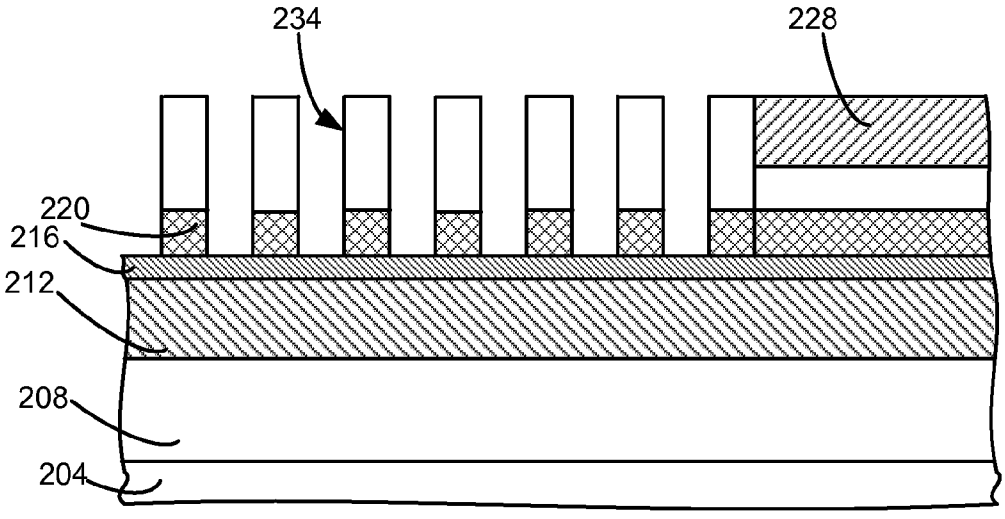


FIG. 3F

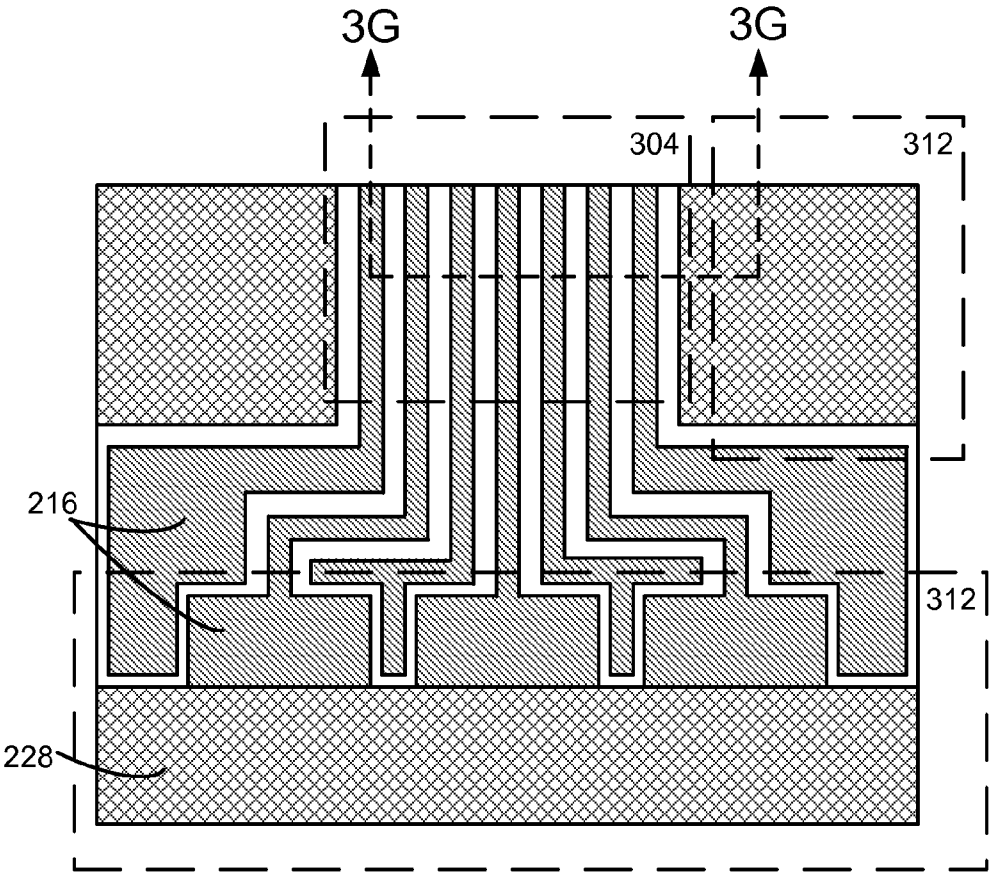


FIG. 2G

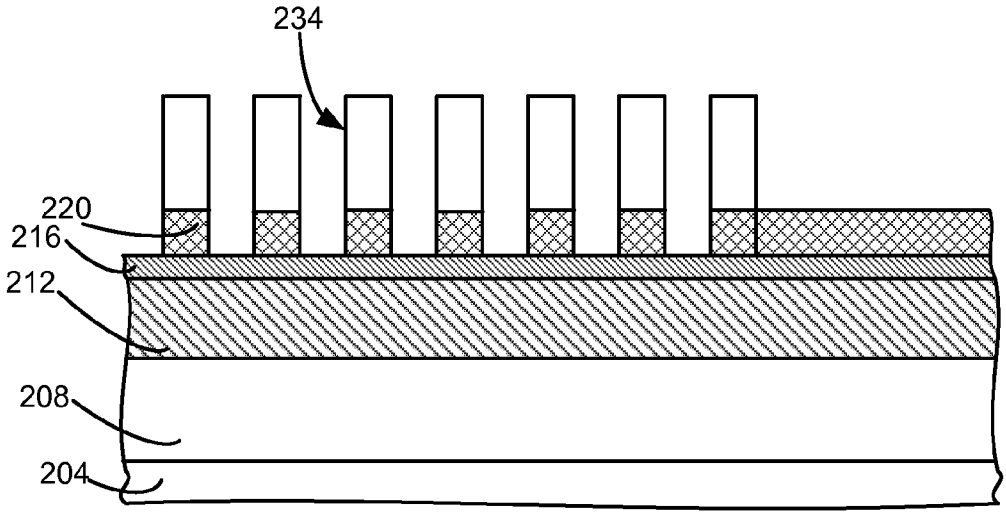


FIG. 3G

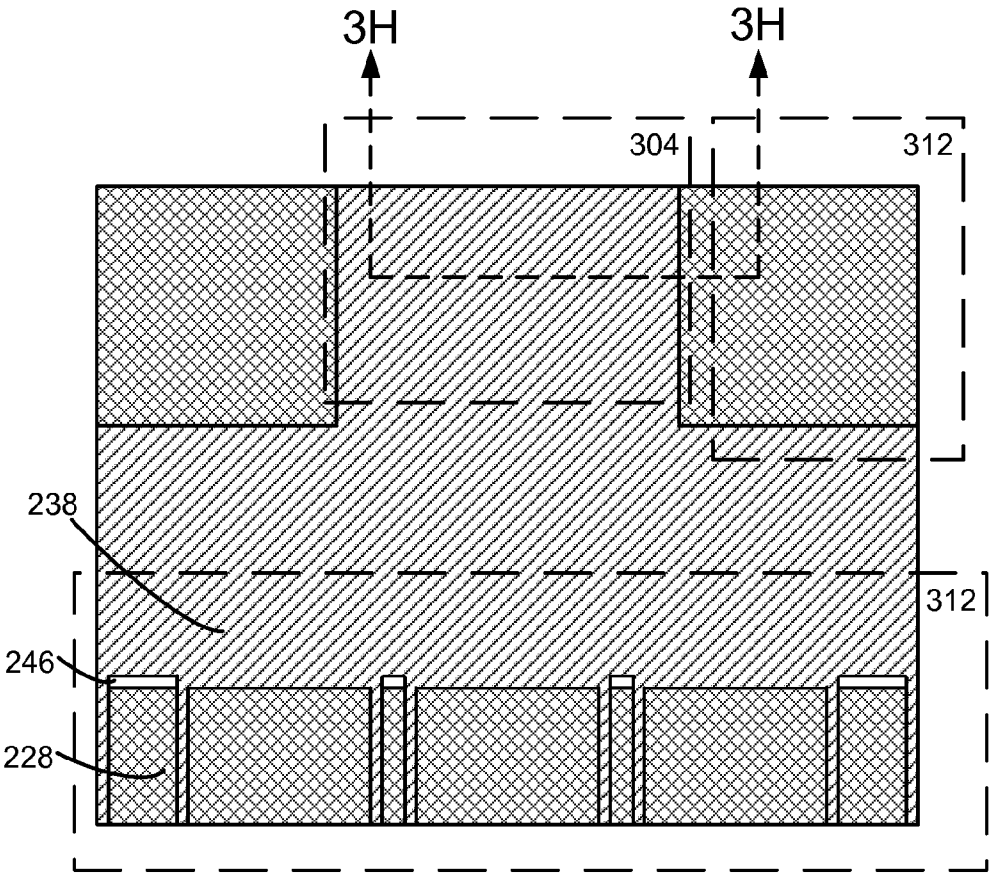


FIG. 2H

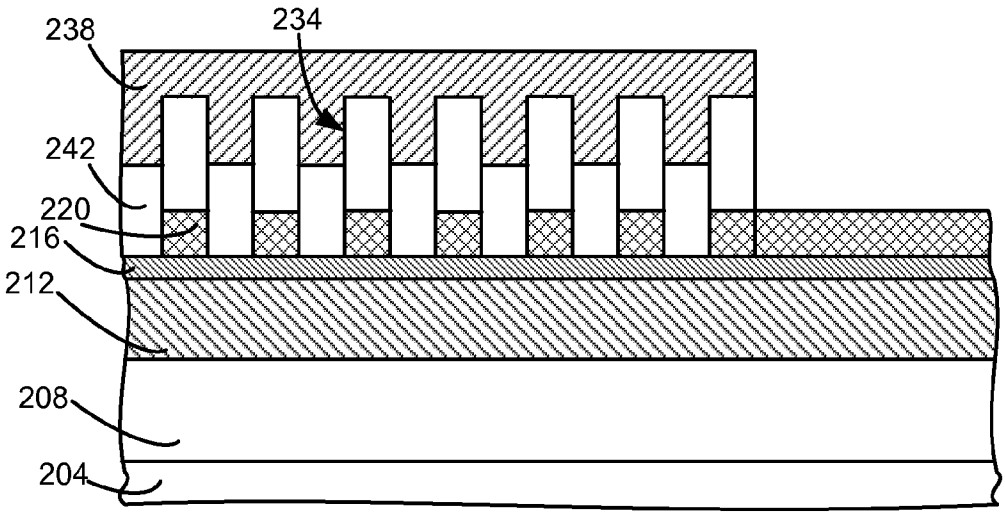


FIG. 3H

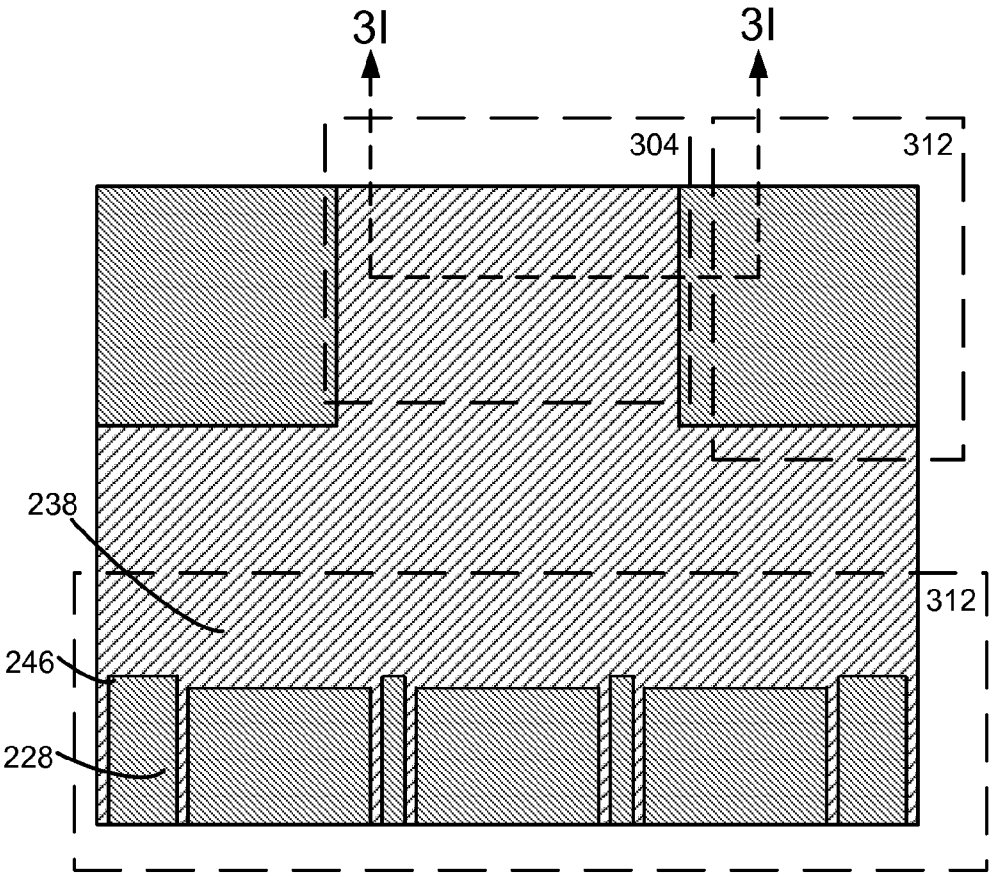


FIG. 2I

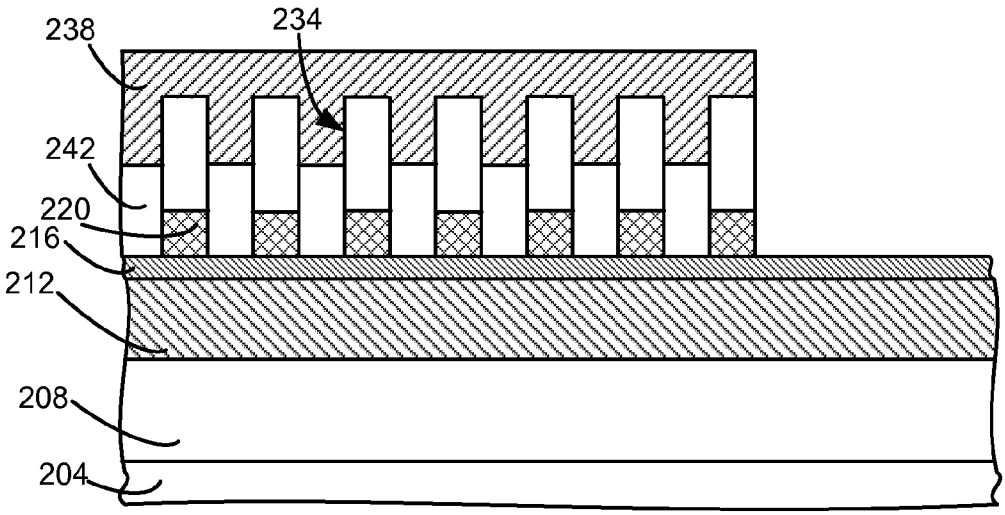


FIG. 3I

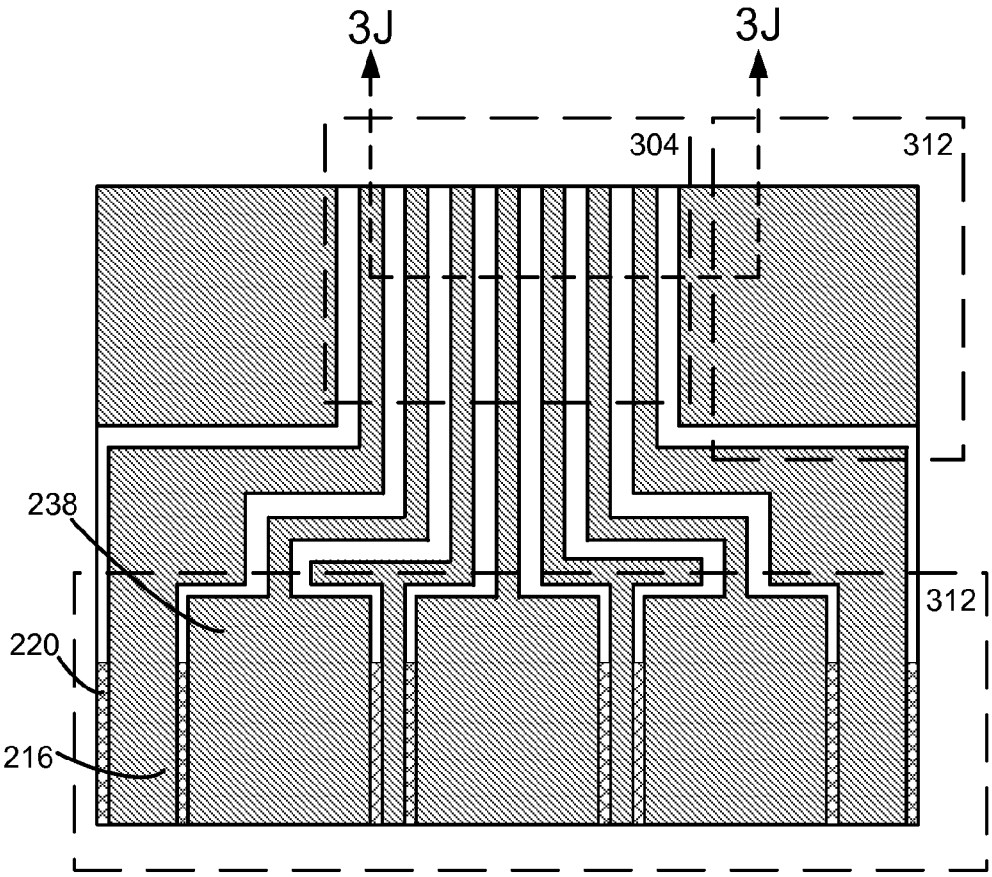


FIG. 2J

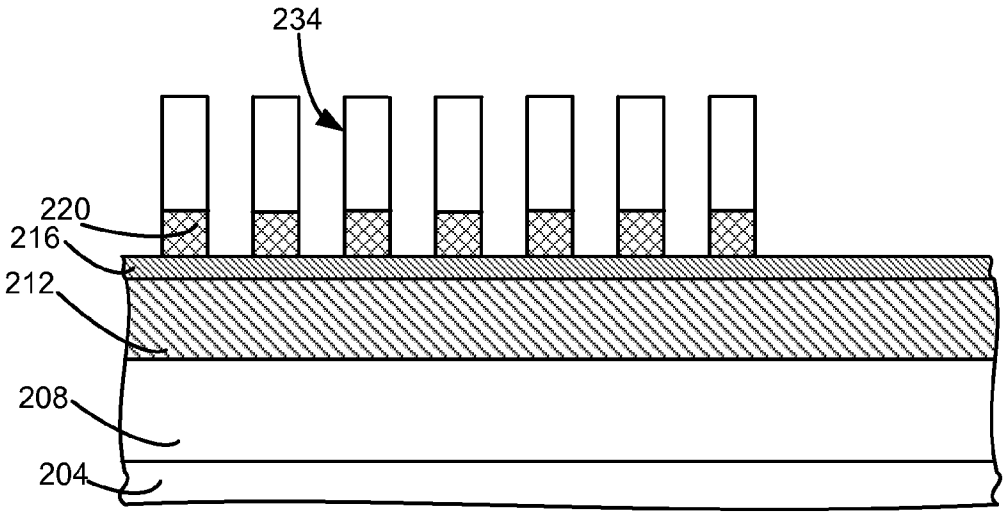


FIG. 3J

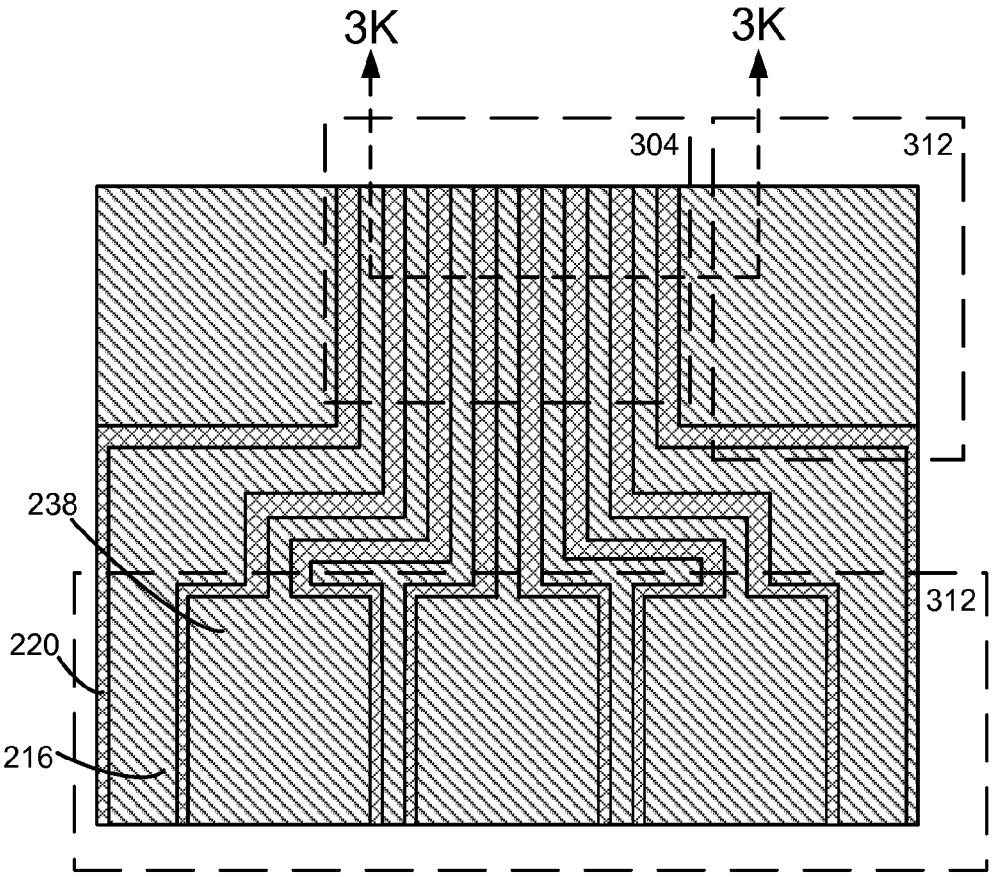


FIG. 2K

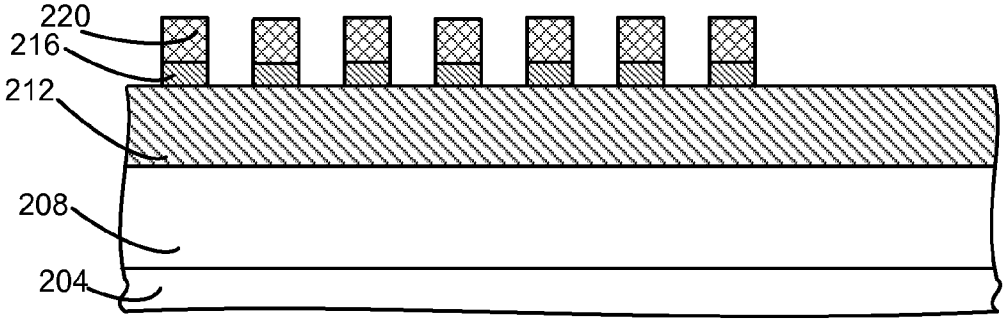


FIG. 3K

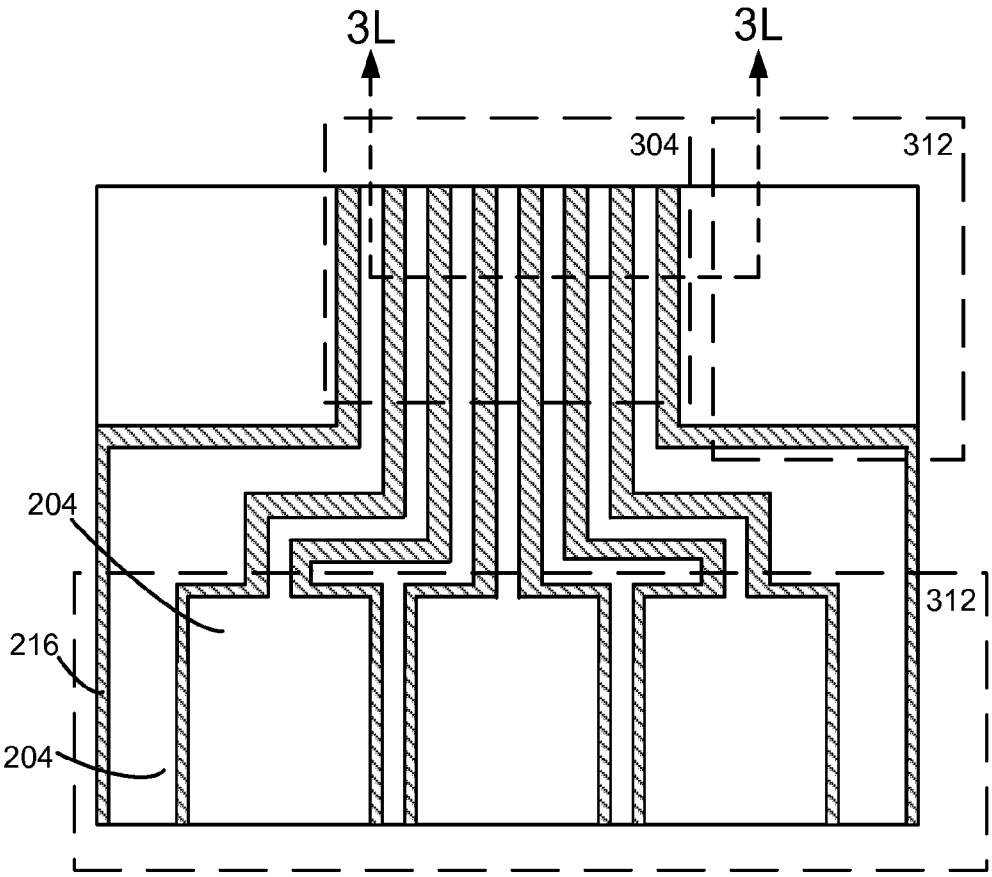


FIG. 2L

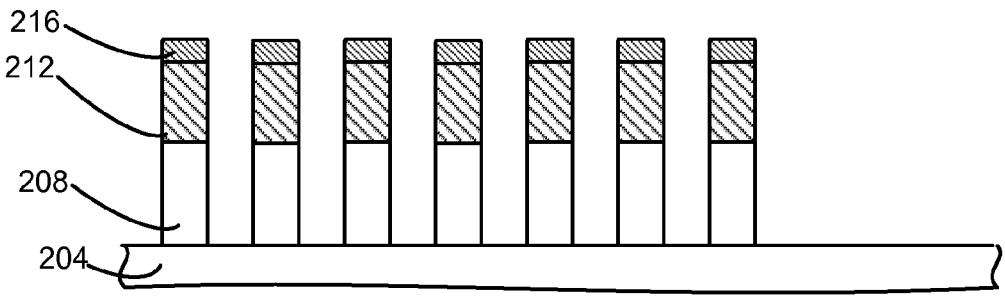


FIG. 3L

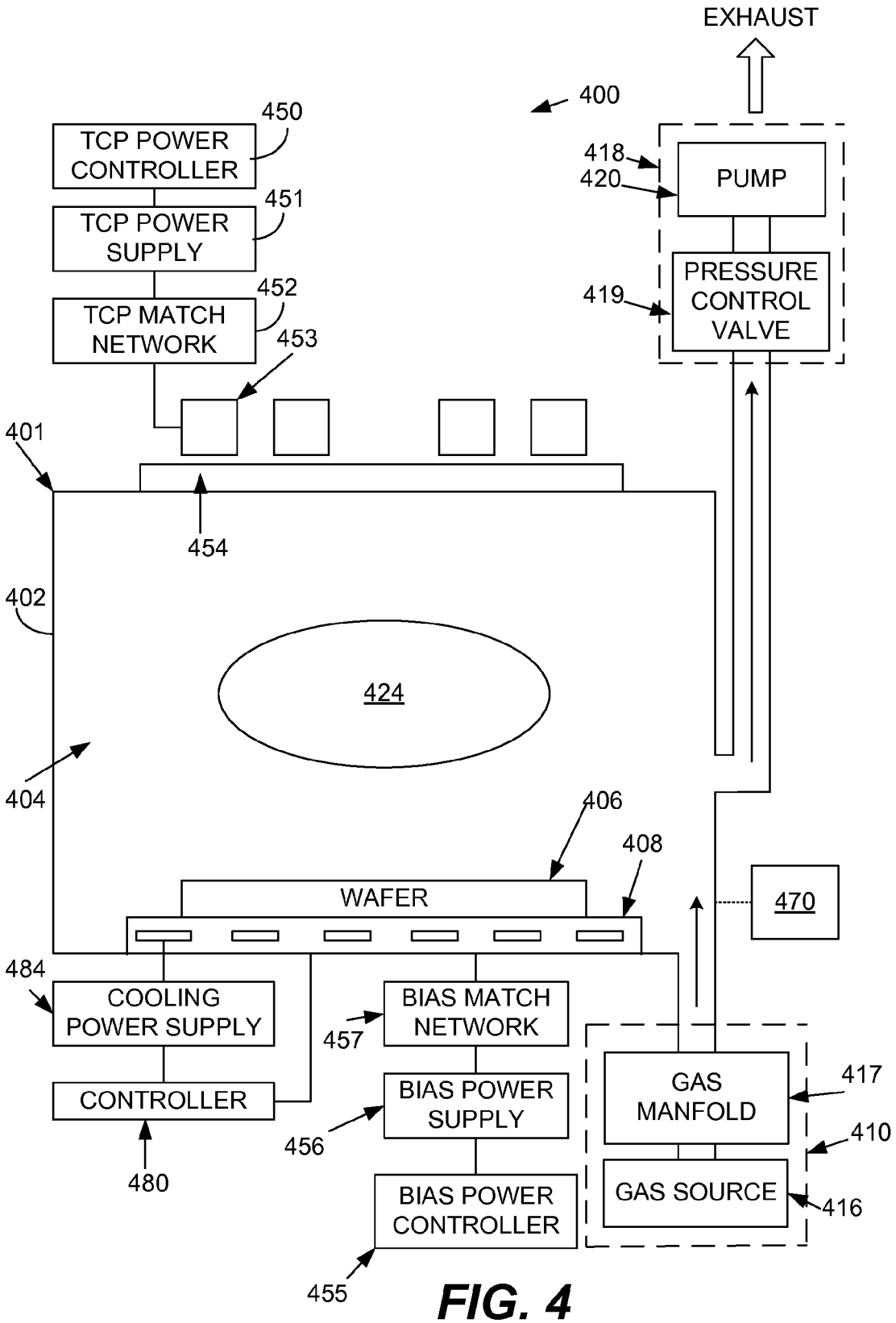

EXHAUST
400
450
TCP POWER CONTROLLER
451
TCP POWER SUPPLY
452
TCP MATCH NETWORK
453
418
420
PUMP
419
PRESSURE CONTROL VALVE
401
454
402
424
404
406
408
WAFER
470
484
COOLING POWER SUPPLY
457
BIAS MATCH NETWORK
CONTROLLER
BIAS POWER SUPPLY
GAS MANFOLD
417
410
456
480
BIAS POWER CONTROLLER
GAS SOURCE
416
455

FIG. 4

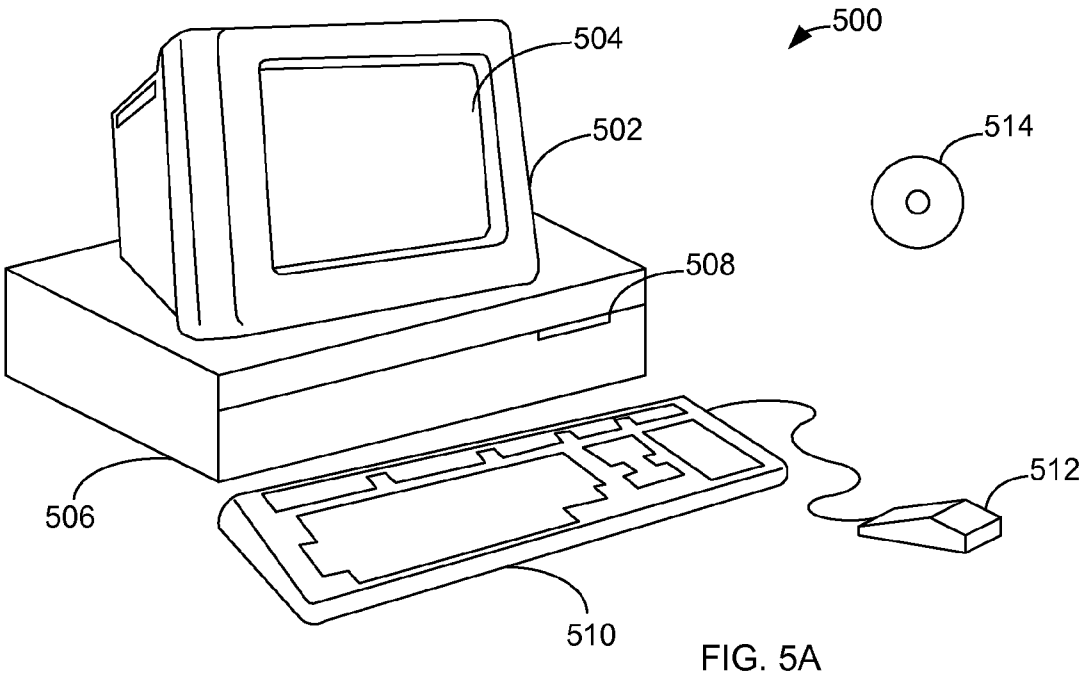

500
504
502
514
508
512
506
510

FIG. 5A

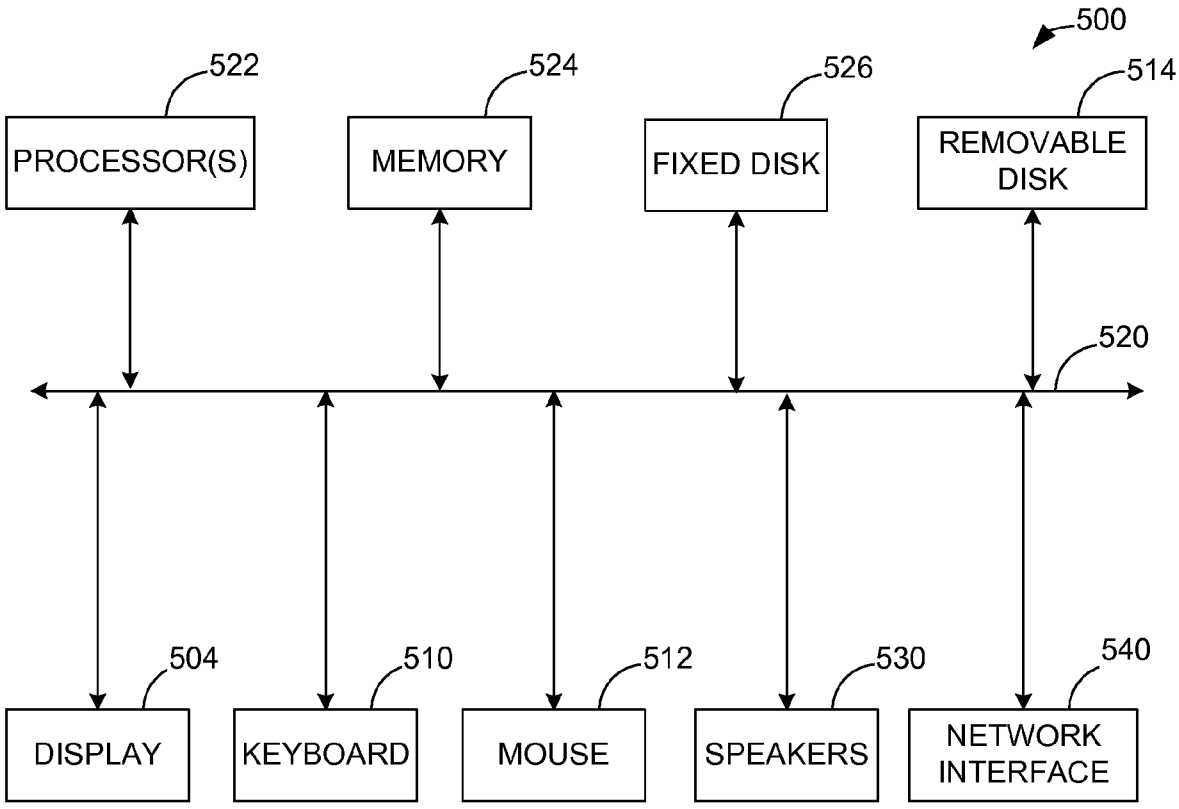

500
522
524
526
514
PROCESSOR(S)
MEMORY
FIXED DISK
REMOVABLE DISK
520
504
510
512
530
540
DISPLAY
KEYBOARD
MOUSE
SPEAKERS
NETWORK INTERFACE

FIG. 5B

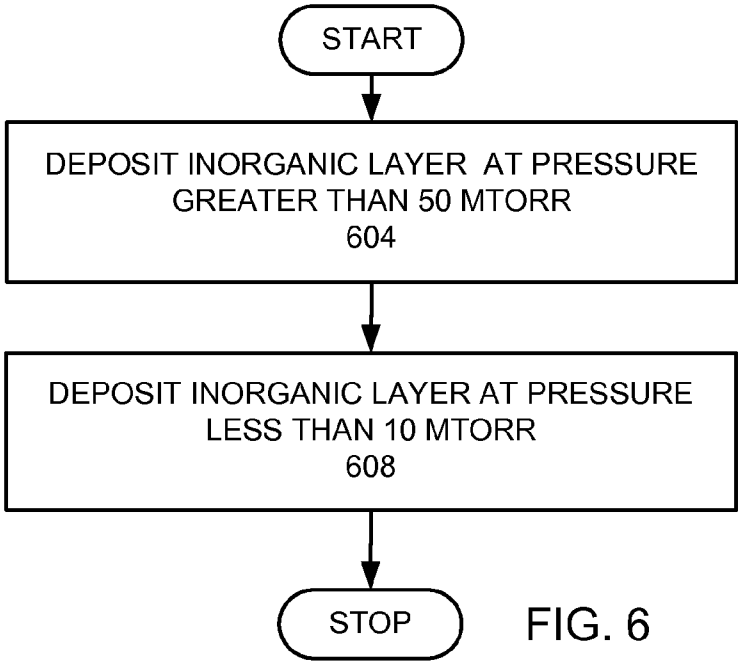

START
DEPOSIT INORGANIC LAYER AT PRESSURE GREATER THAN 50 MTORR
604
DEPOSIT INORGANIC LAYER AT PRESSURE LESS THAN 10 MTORR
608
STOP

FIG. 6

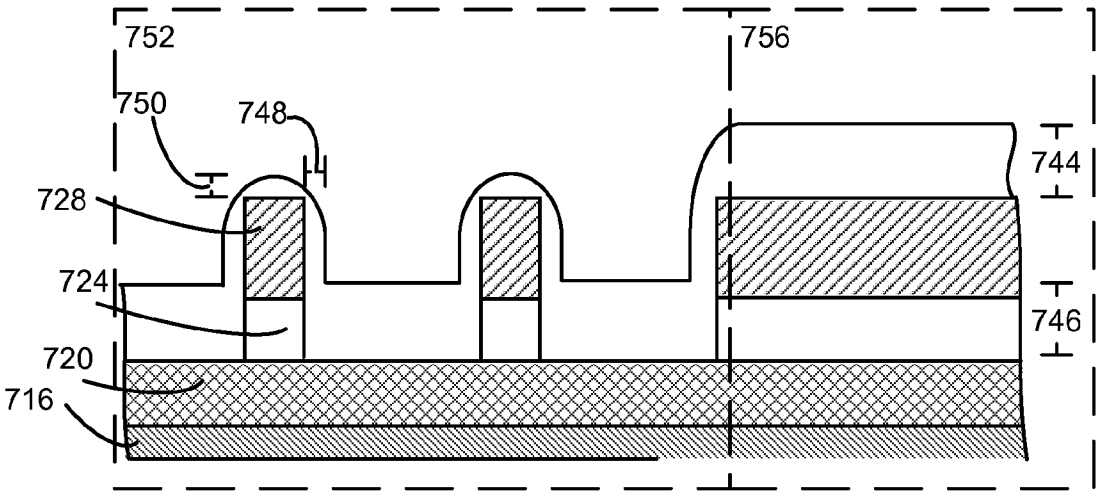

752
756
750
748
744
728
724
746
720
716

FIG. 7A

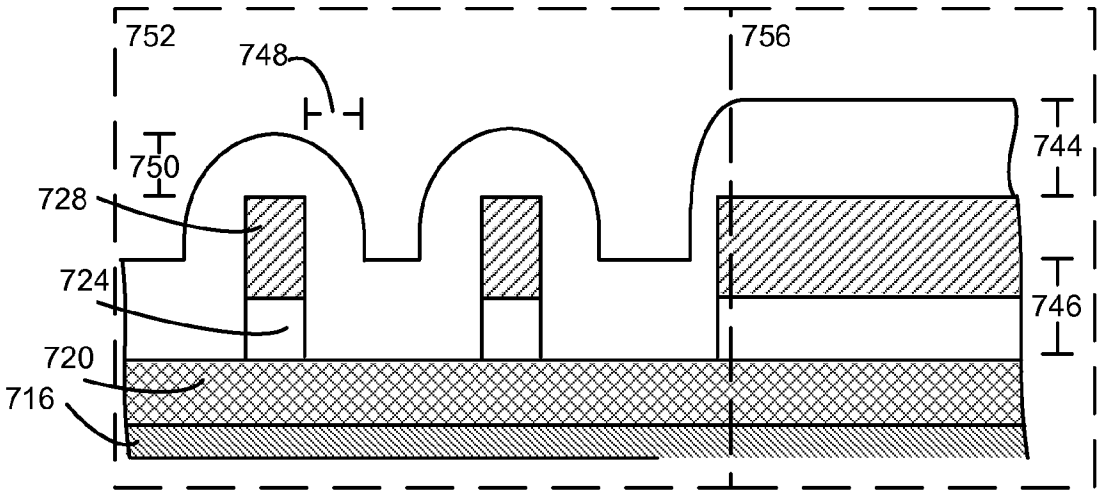

752
748
756
744
750
728
724
746
720
716

FIG. 7B